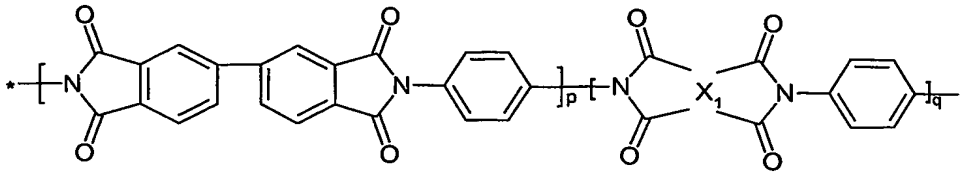
What Is Claimed Is:

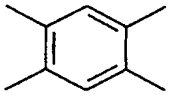
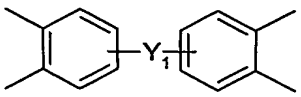
1. A double-sided metallic laminate comprising a metallic layer at one side, a resin layer of a low expansion polyimide having a thermal expansion coefficient of $5x10^{-6}$ to $2.5x10^{-5}$/℃, a resin layer of a thermoplastic polyimide and a metallic layer at the other side.

2. The double-sided metallic laminate according to claim 1, wherein the low thermal expansion polyimide is the following formula 1.

[formula 1]



in which, p>1, q> 0 and p/q=0.4~2.5,

X_1 is  or  , and

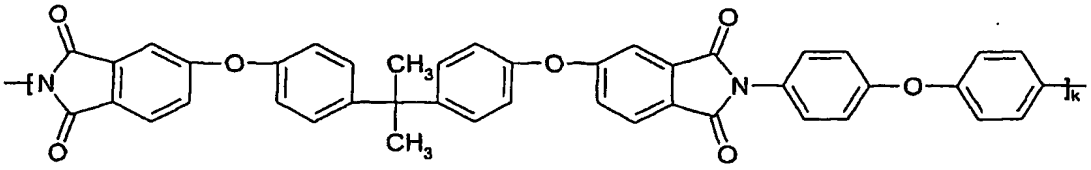
Y_1 is -O- or -CO-.

3. The double-sided metallic laminate according to claim 1, wherein the thermoplastic polyimide has a glass transition temperature of 200 to 250℃.

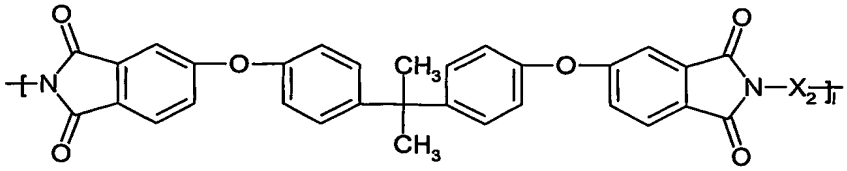
4. The double-sided metallic laminate according to claim 1, wherein the thermoplastic polyimide is a copolymer

including the following formula 2a, formula 2b, formula 2c and formula 2d.

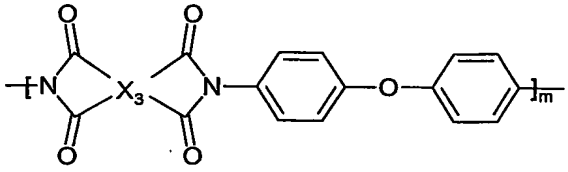
[formula 2a]



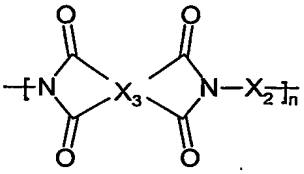
[formula 2b]



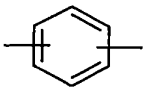
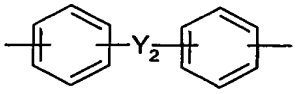
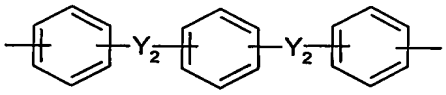
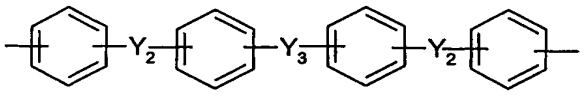
[formula 2c]



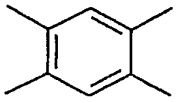
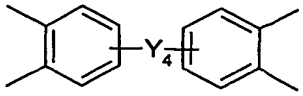
[formula 2d]



in which, $k \geq 1$, ℓ, m, $n \geq 0$, $\ell = m = n \neq 0$, $k \geq \ell$, $k+\ell > 1.5(m+n)$ and $k+m > 1.5(\ell+n)$,

X_2 is at least one selected from the group consisting of  ,  ,  and  ,

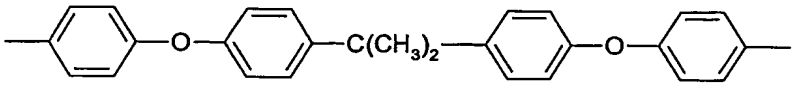
Y_2 and Y_3 are each independently or simultaneously -, -O-, -CO-, -S-, $-SO_2-$, $-C(CH_3)_2-$ or -CONH-,

X_3 is  or  , and

Y_4 is -, -O- or -CO-.

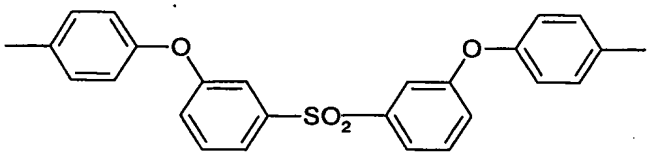
5. The double-sided metallic laminate according to claim 4, wherein the thermoplastic polyimide is the formulae 2a to 2d, in which m, n= 0 and X_2 is the following formula 3.

[formula 3]



6. The double-sided metallic laminate according to claim 4, wherein the thermoplastic polyimide is the formulae 2a to 2d, in which m, n=0 and X_2 is the following formula 4.

[formula 4]



7. The double-sided metallic laminate according to claim 1, wherein the metallic layer is formed of copper.

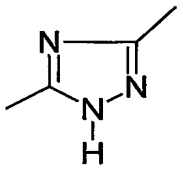
8. The double-sided metallic laminate according to claim 1, which further comprises a resin layer of a polyimide between the metallic layer at one side and a

resin layer of a low expansion polyimide for improving adhesion with a metal.

9. The double-sided metallic laminate according to claim 8, wherein the polyimide for improving adhesion with a metal is a polyimide having a -NH- functional group introduced.

10. The double-sided metallic laminate according to claim 8, wherein the polyimide for improving adhesion with a metal is a polyimide having the following formula 5 introduced.

[formula 5]



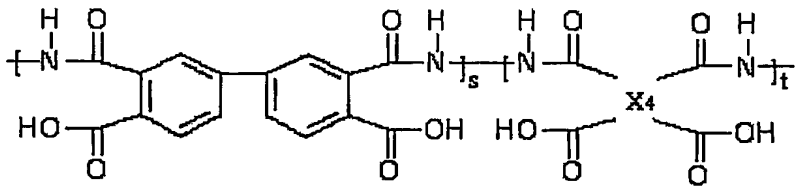
11. The double-sided metallic laminate according to claim 1, wherein the polyimide for improving adhesion with a metal is a copolymer including the formula 2a, formula 2b, formula 2c and formula 2d.

12. A method for manufacturing a double-sided metallic laminate comprising simultaneously or sequentially applying a precursor of a low thermal expansion polyimide

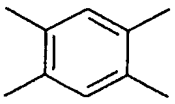
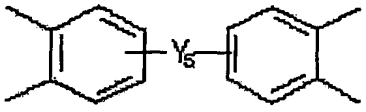
having a thermal expansion coefficient of 5x10-6 to 2.5x10-5/℃ and a precursor of a thermoplastic polyimide on a metal foil to form one side of the double-sided metallic layer, followed by drying and curing, and laminating another metal foil on the resin layer of a thermoplastic polyimide of the resulting one-sided metallic laminate comprising a metal foil layer, a resin layer of a low expansion polyimide and a resin layer of a thermoplastic polyimide, which are sequentially laminated, to form the other side of the double-sided metallic laminate.

13. The method according to claim 12, wherein the precursor of a low thermal expansion polyimide is a copolymer of the following formula 6.

[formula 6]



in which, s>1, t>0 and s/t=0.4~2.5,

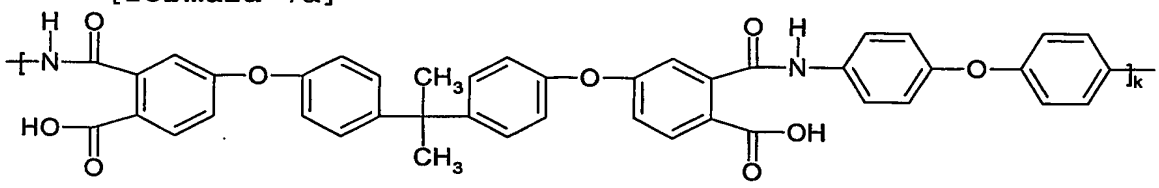
X_4 is  or  , and

Y_5 is -, -O- or -CO-.

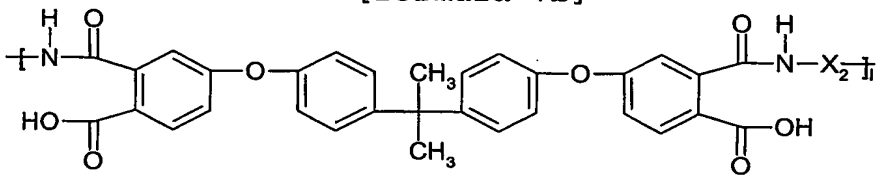
14. The method according to claim 12, wherein the thermoplastic polyimide has a glass transition temperature of 200 to 250℃.

15. The method according to claim 12, wherein the precursor of a thermoplastic polyimide is a copolymer including the following formula 7a, formula 7b, formula 7c and formula 7d.

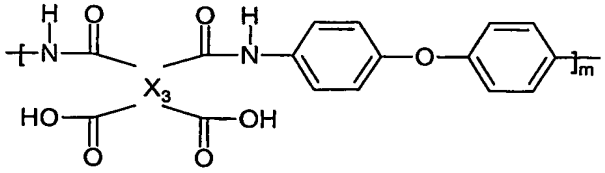
[formula 7a]



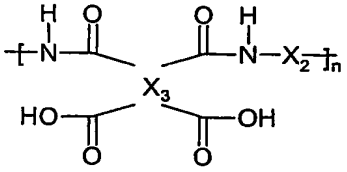
[formula 7b]



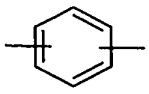
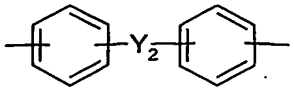
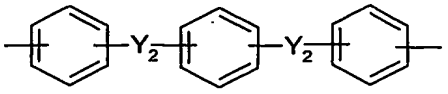
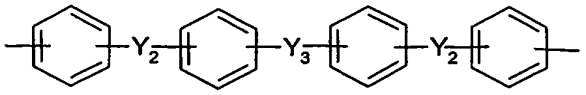
[formula 7c]



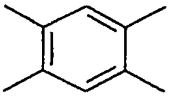
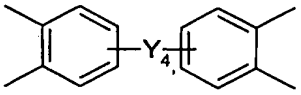
[formula 7d]



in which, $k \geq 1$, ℓ, m, $n \geq 0$, $\ell = m = n \neq 0$, $k \geq \ell$, $k+\ell > 1.5(m+n)$ and $k+m > 1.5(\ell+n)$,

X_2 is at least one selected from the group consisting of  ,  ,  and  ,

Y_2 and Y_3 are each independently or simultaneously -, -O-, -CO-, -S-, $-SO_2-$, $-C(CH_3)_2-$ or -CONH-,

X_3 is  or  , and

Y_4 is -, -O- or -CO-.

16. The method according to claim 15, wherein the precursor of a thermoplastic polyimide is the formulae 7a to 7d, in which m, n=0 and X_2 is the formula 3.

17. The method according to claim 15, wherein the precursor of a thermoplastic polyimide may be the formulae 7a to 7d, in which m, n=0 and X_2 is the formula 4.

18. The method according to claim 12, wherein the precursor applied on the metal film at one side of the double-sided metallic layer is a precursor of a polyimide for improving adhesion with a metal, precursor of a low thermal expansion polyimide having a thermal expansion coefficient of 5x10-6 to 2.5x10-5/℃ and a precursor of a thermoplastic polyimide.

19. The method according to claim 12, wherein the precursor of a polyimide for improving adhesion with a metal is a precursor of a polyimide having a -NH- functional group introduced.

20. The method according to claim 12, wherein the precursor of a polyimide for improving adhesion with a metal is a precursor of a polyimide having the formula 5 introduced.

21. The method according to claim 12, wherein the precursor of a polyimide for improving adhesion with a metal is a copolymer including formula 7a, formula 7b, formula 7c and formula 7d.